### **Overview**

### HP EliteBook x360 830 G6 Notebook PC



- 1. HD and IR Camera (Optional)
- 2. IR camera LEDs (Optional)
- 3. Internal microphones
- 4. Camera Shutter
- 5. HD Camera LED
- 6. Ambient light sensor (Optional)

### Left

- 7. Glass Clickpad
- 8. Smartcard reader (Optional)
- 9. Volume Up/Down
- 10. Vents
- 11. Power Button
- 12. USB 3.1 Gen 1 charging port



## **Overview**



- 1. Power connector
- 2. USB 3.1 Gen 1
- 3. HDMI port (Cable not included)
- 4. USB Type-C™ with Thunderbolt™
- 5. USB Type-C™ with Thunderbolt™

### Right

- 6. Audio Combo Jack
- 7. Nano Security Lock Slot (Lock sold separately)
- 8. SIM card tray<sup>1</sup>
- 9. Touch fingerprint sensor (Optional)

1. All units have a SIM card stray but units that do not support WWAN are shipped with a non-removable SIM slot plug



### Overview

### At a Glance

- Eye catching, Aluminum x360 design with four usage modes that is 0.66 inches (1.69 cm) thin and with a starting weight of 2.97 lbs. (1.35 Kg)
- Choice of 8th Generation Intel® Core™ i3, i5, i7 Processors
- Optional ultrabright, ant-glare touch displays with ambient light sensor
- Choice of displays:
  - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC
  - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC
  - 33.8 cm (13.3") diagonal FHD IPS LED-backlit Anti-Glare glass touch with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC
  - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HP Sure View\*
  - 33.8 cm (13.3") diagonal FHD IPS LED-backlit Anti-Glare glass touch with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HP Sure View\*
- Enterprise grade security with HP Sure Sense, HP SureStart Gen5, HP Privacy Camera, HP Sure View Gen3<sup>1</sup>, HP Sure Run Gen2, HP Sure Recover Gen2<sup>2</sup>, HP Sure Click, SmartCard Reader<sup>2</sup> and Touch Fingerprint reader<sup>2</sup>
- New optional HP Rechargeable Active Pen<sup>2</sup>
- Ultimate connectivity with optional Wi-Fi 6², CAT16 4G/LTE WWAN, and Thunderbolt™ Docking (Dock sold separately)
- Preinstalled with Windows 10 versions or FreeDOS 3.0
- Choice of solid state drives up to 2 TB and DDR4 memory up to 32 GB
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles<sup>3</sup>
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation
- Battery life up to 21 hours<sup>5</sup>
- Passed MIL-STD 810G testing, plus an additional 120,000 hours of reliability testing through HP's Total Test Process<sup>4</sup>
- Instant on/instant off with Modern Connected Standby
- 1. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 2. Sold separately or as an optional feature
- 3. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 4. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 5. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <a href="http://www.bapco.com">http://www.bapco.com</a> for additional details.
- \*Touch-enabled display and Sure View privacy panel will lower actual brightness.

**NOTE:** See important legal disclosures for all listed specs in their respective features sections.



## **Technical Specifications**

### **PRODUCT NAME**

HP EliteBook x360 830 G6 Notebook PC

### OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64<sup>1</sup>

Windows 10 Pro 64 (National Academic Only)2

Windows 10 Home 641

Windows 10 Home Single Language 641

FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

### **PROCESSORS**

Intel® Core™ i3-8145U with Intel® UHD Graphics 620 (2.1 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)<sup>3,4,5,6</sup>

Intel® Core™ i5-8265U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)<sup>3,4,5,6</sup>

Intel® Core™ i5-8365U vPro™ processor with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) 3,4,5,6

Intel® Core™ i7-8565U with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)<sup>3,4,5,6</sup>

Intel® Core™ i7-8665U vPro™ processor with Intel® UHD Graphics 620 (1.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) 3,4,5,6

### **Processor Family**

8th Generation Intel® Core™ i7 processor (i3-8145U)6

8th Generation Intel® Core™ i7 processor (i7-8665U and i7-8565U)<sup>6</sup>

8th Generation Intel® Core™ i5 processor (i5-8365U and i5-8265U)6

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode. 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <a href="http://www.intel.com/technology/turboboost">http://www.intel.com/technology/turboboost</a> for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



## **Technical Specifications**

### **CHIPSET**

Chipset is integrated with processor

### **GRAPHICS**

### Integrated

Intel® UHD Graphics 6207

### Supports

Support HD decode, DX12, HDMI 1.4b8, HDCP 2.2

- 7. HD content required to view HD images.
- 8. HDMI cable sold separately.

### **DISPLAY**

#### **Touch**

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC with HD camera (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC with HD camera for WWAN (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Ambient Light Sensor and HD IR camera (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Ambient Light Sensor and HD IR camera for WWAN (1920 x 1080)<sup>7,9,10</sup>

33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Ambient Light Sensor and HD IR camera for WWAN (1920 x 1080)<sup>7,9,10</sup>

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD IR webcam (1920 x 1080)<sup>7,9,10,11\*</sup>

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD IR webcam for WWAN (1920 x 1080)<sup>7,9,10,11\*</sup> HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD IR webcam for WWAN (1920 x 1080)<sup>7,9,10,11\*</sup>

### **HDMI 1.4b**

Supports resolution up to 4k @ 30Hz

- 7. HD content required to view HD images.
- 9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 10. Sold separately or as an optional feature.
- 11. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- \*Touch-enabled display and Sure View privacy panel will lower actual brightness.



## **Technical Specifications**

Docking station model	Total number of supported displays (Including the notebook) display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	Dual 4k (4096 x 2160) only with: • 1 DP + TB port or • USB-C alt mode + TB port  Dual 4K (3840 x 2160) with any of the DP, TB or USB-C alt mode video ports
HP Elite USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

### STORAGE AND DRIVES

### **Primary M.2 Storage**

128 GB SATA-3 SS TLC12

256 GB PCIe® NVMe™ SS Value<sup>12</sup>

256 GB PCIe® Gen3x4 NVMe™ SS TLC12

256 GB SATA-3 SED SS TLC<sup>12</sup>

256 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 16 GB Intel® Optane™ memory H10<sup>12,13,14</sup>

512 GB PCIe® NVMe™ SS Value12

512 GB PCIe® Gen3x4 NVMe™ SS TLC12

512 GB PCIe® Gen3x4 NVMe™ SED SS TLC12

512 GB SATA-3 SS TLC (FIPS 140-2)12

512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10(Planned to be available Q2 2019)12,13,14

1 TB PCIe® Gen3x4 NVMe™ SS TLC12

2 TB PCIe® Gen3x4 NVMe™ SS TLC12

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

13. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

14. Intel® Optane™ memory H10 only for Intel® PCIe® NVMe™ QLC M.2 SSD.



### **Technical Specifications**

### **MEMORY**

### **Maximum Memory**

32 GB DDR4-2400 SDRAM15

### Memory

32 GB DDR4-2400 SDRAM (2 x 16 GB)<sup>15</sup>
16 GB DDR4-2400 SDRAM (1 x 16 GB)<sup>15</sup>
16 GB DDR4-2400 SDRAM (2 x 8 GB)<sup>15</sup>
8 GB DDR4-2400 SDRAM (1 x 8 GB)<sup>15</sup>
8 GB DDR4-2400 SDRAM (2 x 4 GB)<sup>15</sup>
4 GB DDR4-2400 SDRAM (1 x 4 GB)<sup>15</sup>

### **Memory Slots**

2 SODIMM Both slots are upgradeable System runs at 2400 for Intel® 8th Generation processors Supports Dual Channel Memory

15. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

### **NETWORKING/COMMUNICATIONS**

#### **WLAN**

Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, vPro $^{\text{IM}10,16}$  Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro $^{\text{IM}}$  10,16 Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) and Bluetooth® 5 Combo, vPro $^{\text{IM}}$ 10,20 Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) Bluetooth® 5 Combo, non-vPro $^{\text{IM}}$ 10,20

### **WWAN**

Intel® XMM™ 7262 LTE-Advanced Cat 6<sup>17</sup>
Intel® XMM™ 7360 LTE-Advanced Cat 9<sup>17</sup>
Intel® XMM™ 7560 LTE-Advanced Pro Cat 16<sup>19</sup>

#### NFC

NXP NPC300 Near Field Communication Module<sup>10</sup>

### Miracast

Native Miracast Support18

- 10. Sold separately or as an optional feature.
- 16. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
- 17. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 18. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 19. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and



## **Technical Specifications**

availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

20. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

### **AUDIO/MULTIMEDIA**

### Audio

Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 2 Integrated Stereo Speakers (74 Db)

### Camera

HD camera<sup>7</sup> HD IR camera<sup>7</sup>

7. HD content required to view HD images.

### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

### Keyboard

HP Premium Collaboration Keyboard, backlit and spill resistant with drain

### **Pointing Device**

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

### **Function Keys**

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Calendar

Share/Present

Call Answer

Call End

### **Hidden Function Keys**

Fn+R - Break

Fn+S - Sys Rq



## **Technical Specifications**

Fn+C - Scroll Lock

Fn+E - Insert

Fn+W - Pause

### SOFTWARE AND SECURITY

#### **Preinstalled Software**

#### BIOS

HP BIOSphere Gen5<sup>21</sup>

HP Drive Lock & Automatic Drive Lock<sup>22</sup>

**BIOS Update via Network** 

Master Boot Record Security

**Power On Authentication** 

Secure Erase<sup>23</sup>

Absolute Persistence Module<sup>24</sup>

Pre-boot Authentication

### Software

HP Native Miracast Support<sup>25</sup>

**HP Connection Optimizer** 

**HP Image Assistant** 

**HP Hotkey Support** 

**HP JumpStart** 

HP Support Assistant<sup>26</sup>

**HP Noise Cancellation Software** 

Buy Office (Sold separately)

### **Manageability Features**

HP Driver Packs<sup>27</sup>

**HP System Software Manager (SSM)** 

HP BIOS Config Utility (BCU)

**HP Client Catalog** 

HP Manageability Integration Kit Gen3<sup>28</sup>

HP Cloud Recovery<sup>29</sup>

### **Client Security Software**

HP Client Security Manager Gen530

HP Fingerprint Sensor<sup>31</sup>

**HP Power On Authentication** 

Windows Defender<sup>32</sup>

### **Security Management**

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

SATA 0,1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click<sup>33</sup>

HP Sure Start Gen5<sup>34</sup>

HP Sure Run Gen2<sup>35</sup>

HP Sure Recover Gen2<sup>36</sup>



## **Technical Specifications**

HP Sure Sense<sup>37</sup>

### **TPM**

Model: Infineon SLB9670

Version: 7.85 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes

### **Smartcard Reader**

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

### **IPv6 Compliance**

Yes

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to <a href="http://hp.com/support">http://hp.com/support</a>, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

- 21. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- 22 HP Automatic Drive Lock is not supported on NVMe drives
- 23. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 24. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 25. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 26. HP Support Assistant requires Windows and Internet access.
- 27. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 28. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 29. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 30. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 31. HP Fingerprint Sensor sold separately or as an optional feature.
- 32. Windows Defender Opt in and internet connection required for updates.



## **Technical Specifications**

- 33. HP Sure Click is available on select HP platforms and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 34. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- 35. HP Sure Run Gen2: See product specifications for availability.
- 36. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
- 37. HP Sure Sense requires Windows 10. See product specifications for availability.

### **POWER**

### **Power Supply**

HP Smart 45 W External AC power adapter<sup>38</sup>
HP Smart 45 W External AC power adapter, 2-prong (Japan only)<sup>38</sup>
HP Smart 65 W External AC power adapter<sup>38</sup>
HP Smart 65 W EM External AC power adapter<sup>38</sup>
HP 45 W USB Type-C<sup>™</sup> adapter<sup>38</sup>
HP 65 W USB Type-C<sup>™</sup> adapter<sup>38</sup>

### **Primary Battery**

HP Long Life 4-cell, 53 Wh Li-ion<sup>39</sup>

### **Battery Life**

Up to 21 hours (Intel® 8th Generation CPU and 4-cell 53 WHr battery)<sup>40</sup>

### **Power Cord**

2-wire plug - 1m3
3-wire plug - 1m
3-wire plug - 1.8m
Duckhead power cord - 1 m
Duckhead power cord - 1.8 m

- 38. Availability may vary by country.
- 39. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 40. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <a href="http://www.bapco.com">http://www.bapco.com</a> for additional details.

### **WEIGHTS & DIMENSIONS**

### **Product Weight**

Starting weight 2.97 lbs<sup>35</sup> 1.35 kgs<sup>41</sup>

NOTE: Starting weight configuration includes FHD 400 nits BrightView Touch, 53 Wh battery, 4 GB, 128 GB SSD, HD + IR camera, No FPS, with WWAN Antenna, No NFC, and No Pen



## **Technical Specifications**

### Mainstream weight

3.13 lbs351.42 kas41

NOTE: Mainstream weight configuration includes FHD 250 nits BrightView Touch, 53 Wh battery, 4 GB, 128 GB SSD, HD Camera, No FPS, with WWAN Antenna, No NFC and No Pen

### Product Dimensions (w x d x h)

12.07 x 8.47 x 0.66 in 30.66 x 21.52 x 1.69 cm

41. Weight will vary by configuration.

### **PORTS/SLOTS**

2 USB 3.1 Type-C™ with Thunderbolt™ support

2 USB 3.1 Gen 1 (1 Charging)

1 HDMI 1.4b8

1 External Nano SIM tray (Optional)10

1 Headphone/microphone combo

1 Smartcard reader (Optional)<sup>10</sup>

1 AC power

Nano Security Lock Slot (Lock sold separately)

### Sensors

Accelerometer Magnetometer Gyro ALS (ambient light sensor) Hall Sensor

### 8. HDMI cable sold separately

10. Sold separately or as an optional feature.

### **SERVICE AND SUPPORT**

HP offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <a href="http://www.hp.com/support/batterywarranty">http://www.hp.com/support/batterywarranty</a>/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. 42

42. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



**Technical Specifications** 



## **Technical Specifications**

### **SYSTEM UNIT**

Stand-Alone Power Nominal Operating AC 19V

Requirements (AC Power) Voltage

Average Operating Power Win10 Integrated Graphics Yes

Max Operating Power UMA < 65W

**Temperature Operating** 32° to 95° F (0° to 35° C)

**Non-operating** -4° to 140° F (-20° to 60° C)

**Relative Humidity Operating** 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

**Shock Operating** 40 G, 2 ms, half-sine

**Non-operating** 200 G, 2 ms, half-sine

**Random Vibration Operating** 0.75 grms **Non-operating** 1.50 grms

Altitude (unpressurized) Operating -50 to 10,000 ft (-15.24 to 3,048 m)

**Non-operating** -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard UL Yes Certifications CSA Yes

FCC Compliance Yes ENERGY STAR® Yes<sup>43</sup>

**EPEAT® 2019** Yes, Silver in U.S.<sup>44</sup>

ICES Yes
Australia Yes
NZ A-Tick Compliance Yes
CCC Yes

CCC Yes
Japan VCCI Compliance Yes
KC Yes
BSMI Yes
CE Marking Compliance Yes
BNCI or BELUS Yes
CIT Yes
GOST Yes

Saudi Arabian Compliance

(ICCP)

SABS Yes

43. Configurations of the HP EliteBook x360 830 G6 that are ENERGY STAR® certified are identified as HP EliteBook x360 830 G6 ENERGY STAR® on HP websites and on http://www.energystar.gov.

Yes

44. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.



## **Technical Specifications**

Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:  • IT ECO declaration  • US ENERGY STAR®  • US Federal Energy Management Program (FEMP)  • EPEAT® 2019 Silver registered in the United States. Based on EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. See <a href="http://www.epeat.net">http://www.epeat.net</a> for registration status in your country.  • TCO Certified Edge  • China Energy Conservation Program (CECP)  • China State Environmental Protection Administration (SEPA)  • Taiwan Green Mark  • Korea Eco-label  • Japan PC Green label*				
	System Configuration  Energy Consumption (in accordance with US		r the Energy Consumption an tebook model is based on a "			
	ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
	Normal Operation (Sort idle)	4.26	4.42	4.3		
	Normal Operation (Long idle)	2.66	2.77	2.69		
	Sleep	0.88	0.92	0.9		
	Off	Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.				
	Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
	Normal Operation (Short idle) Normal Operation	9	15 9	15 9		
	(Long idle)		-			
	Sleep	3	3	3		
	Off	1	1	1		



service level is attained for one hour.

\*NOTE: Heat dissipation is calculated based on the measured watts, assuming the

## **Technical Specifications**

Declared Noise		Sound Power	Sound Pressure	
Emissions	(L <sub>pAm</sub> , decibels)			
(in accordance with ISO 7779 and ISO 9296)				
Typically Configured — Idle		2.5 15		
Fixed Disk – Random writes		2.6	15	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years.  Upgradeable features and/or components contained in the product may include:  3 USB ports  1 PC card slot (type I/II)  1 ExpressCard/54 slot  1 IEEE 1394 Port  2 SODIMM memory slots  Optional expansion base docking station  1 multi-bay II storage port  Interchangeable HDD  Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC  Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight  Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Silver level, see <a href="http://www.epeat.net">http://www.epeat.net</a></li> <li>Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043.</li> <li>This product contains 5.69% post-consumer recycled plastic (by wt.)</li> <li>This product is 96.4% recycle-able when properly disposed of at end of life.</li> </ul>			
Packaging Materials	External: PAPER/Corrugated 264			
	Internal:	PLASTIC/EPE (Expanded	Polyethylene)	47
	PLASTIC/Polypropylene - PP 3			3
	PLASTIC/Polyethylene low density - LDPE 14			14



## **Technical Specifications**

recillicat 5p	ecincations	
recinical Sp	Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_spe cifications.html):  Asbestos Certain Azo Colorants Certain Brominated Flame Retardants — may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel — finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOS) Polychlorinated Terphenyls (PCT)
		<ul> <li>Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.</li> <li>Radioactive Substances</li> <li>Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)</li> </ul>
	Packaging Usage	<ul> <li>HP follows these guidelines to decrease the environmental impact of product packaging: <ul> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.</li> <li>Eliminate the use of ozone-depleting substances (ODS) in packaging materials.</li> <li>Design packaging materials for ease of disassembly.</li> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> <li>Use readily recyclable packaging materials such as paper and corrugated materials.</li> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul> </li></ul>



## **Technical Specifications**

End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.  The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at http://www.hp.com/go/recyclers. These instructions may be used by recycler and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:  Global Citizenship Report     http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications     http://www8.hp.com/us/en/hp-     information/environment/ecolabels.html ISO 14001 certificates:     http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755

### **DISPLAYS**

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 13.3 inch diagonal FHD WLED BrightView UWVA 72 percent cg 400 nits eDP 1.4+PSR2 ultraslim 

 Outline Dimensions (W x H x D)
 299.06 x 185.54 (max.)

 Active Area
 293.76 x 165.24

Weight 170 g max. (panel only)

Diagonal Size13.3"Thickness2.0 mm

**Interface** eDP 1.4 w/ PSR2 (2 lane)

Surface Treatment BrightView Glass

**Touch Enabled** Yes

**Contrast Ratio** 1500:1 (typical)

Refresh Rate60 HzBrightness400 nits typ.Pixel Resolution1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB

Backlight WLED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85



## **Technical Specifications**

Panel LCD 13.3 inch diagonal FHD WLED Anti-glare UWVA 72 percent cg 400 nits eDP 1.4+PSR2 ultraslim 

 Outline Dimensions (W x H x D)
 299.06 x 185.54 (max.)

 Active Area
 293.76 x 165.24

Weight 170 g max. (panel only)

Diagonal Size13.3"Thickness2.0 mm

Interface eDP 1.4 w/ PSR2 (2 lane)

**Surface Treatment** Anti-glare Glass

**Touch Enabled** Yes

Contrast Ratio 1500:1 (typical)

Refresh Rate 60 Hz

**Brightness** 400 nits typ. Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB

Backlight WLED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD WLED BrightView UWVA 45 percent cg 250 nits eDP slim **Outline Dimensions (W x H x D)** 300.56 x 187.77 max. (w/ PCB & w/o bracket)

Active Area 293.76 x 165.24 typ.
Weight <260 max. (panel only)

**Diagonal Size** 13.3"

Thickness3.0 mm max.InterfaceeDP 1.2 (2 lane)Surface TreatmentBrightView Glass

**Touch Enabled** Yes

Contrast Ratio600:1 (typ)Refresh Rate60 HzBrightness250 nit typ

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB

Backlight WLED

**Color Gamut Coverage** 45% of NTSC

Color Depth 6 bit

Viewing Angle UWVA 85/85/85



## **Technical Specifications**

Panel LCD 13.3 inch diagonal FHD WLED BrightView UWVA 72 percent cg 1000 nits eDP 1.4+PSR2 flat Privacy 

 Outline Dimensions (W x H x D)
 298.76 x 186.04 mm (typ.)

 Active Area
 293.76 x 165.24 mm (typ.)

Weight 255 g (max)

Diagonal Size 13.3 inch

Thickness 3.0 mm (max)
Interface eDP 1.4

**Surface Treatment** BrightView Glass

Touch Enabled YES

Contrast Ratio2000:1(typ.)Refresh Rate60 HzBrightness\*1000 nits

Pixel Resolution 1920 x 1080(FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

**Color Gamut Coverage** 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD WLED Anti-Glare UWVA 72 percent cg 1000 nits eDP 1.4+PSR2 flat Privacy Outline Dimensions (W x H x D) 298.76 x 186.04 mm (typ.)

**Active Area** 293.76 x 165.24 mm (typ.)

Weight 255 g (max)
Diagonal Size 13.3 inch
Thickness 3.0 mm (max)
Interface eDP 1.4

**Surface Treatment** Anti-glare Glass

**Touch Enabled** YES

Contrast Ratio2000:1 (typ.)Refresh Rate60 HzBrightness1000 nits

Pixel Resolution 1920 x 1080(FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

**Color Gamut Coverage** 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85



<sup>\*</sup>Touch-enabled display and Sure View privacy panel will lower actual brightness.

<sup>\*</sup>Touch-enabled display and Sure View privacy panel will lower actual brightness.

## **Technical Specifications**

### STORAGE AND DRIVES

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128 GB 2280 M2 SATA-3 TLC Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfaceATA-8, SATA 3.0Maximum Sequential ReadUp To 520 MB/sMaximum Sequential WriteUp To 450 MB/sLogical Blocks250,069,680

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

SSD 256 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 3167 MB/sMaximum Sequential WriteUp To 1663 MB/sLogical Blocks500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 256 GB 2280 M2 SATA-3 Self Encrypted OPAL2 TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface ATA-8, SATA 3.0
Maximum Sequential Read Up To 530 MB/s
Maximum Sequential Write Up To 515 MB/s
Logical Blocks 500.118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]



## **Technical Specifications**

Features DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 600 MB/sLogical Blocks500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type MLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2600 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB 2280 M2 SATA- Form Factor
3 TLC FIPS Capacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface ACS-3, SATA 3.2
Maximum Sequential Read Up To 530 MB/s
Maximum Sequential Write Up To 400 MB/s
Logical Blocks 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP



## **Technical Specifications**

SSD 512 GB 2280 PCIe-3x4 Form Fac NVMe Self Encrypted OPAL2 Capacity TLC

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Weight 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Up To 2900 MB/s

Maximum Sequential Write Up To 1400 MB/s

Logical Blocks 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 1 TB 2280 PCle-3x4 NVMe TLC SS Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3480 MB/sMaximum Sequential WriteUp to 2800 MB/sLogical Blocks2,000,409,264

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM: L1.2

SSD 2 TB 2280 PCIe-3x4 NVMe TLC SS Form Factor M.2 2280
Capacity 2 TB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up to 3000 MB/s
Maximum Sequential Write Up to 2100 MB/s
Logical Blocks 3,907,029,168

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

**Height** 0.09 in (2.3 mm)



## **Technical Specifications**

Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up to 1700 MB/s
Maximum Sequential Write Up to 1500 MB/s
Logical Blocks 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB PCIe NVMe + 32 GB Optane Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1300 MB/sLogical Blocks1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2



## **Technical Specifications**

### **NETWORKING/COMMUNICATIONS**

Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo¹. vPro™<sup>10,14</sup>

Intel® Wireless-AC 9560 Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi® certified

Interoperability
Frequency Band

• 802.11b/g/n 2.402 – 2.482 GHz

• 802.11a/n

4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

**Data Rates** 

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation

**Direct Sequence Spread Spectrum** 

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security<sup>3</sup>

•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

**Network Architecture** 

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power<sup>2</sup> • 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

**Power Consumption** 

•Transmit mode 2.0 W •Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW



## **Technical Specifications**

Radio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity** <sup>3</sup> 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

**Antenna type** High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

**Dimensions** Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (–10° to 70° C)

Non-operating  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

**Altitude** Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

### HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification4.0/4.1/4.2 CompliantFrequency Band2402 to 2480 MHzNumber of AvailableLegacy: 0~79 (1 MHz/CH)ChannelsBLE: 0~39 (2 MHz/CH)

**Signaling Data Rate** Legacy: 3 Mbps signaling data rate<sup>1</sup> 2.17 Mbps

BLE: 1 Mbps signaling data rate 1 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.



### **Technical Specifications**

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface USB 2.0 compliant

**Bluetooth Software** 

Supported Link Topology Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C. Section 15.247 & 15.249

Power Management Certifications ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

10. Sold separately or as an optional feature.

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo¹, non-vPro™10,14

Wireless LAN Standards IEEE 802.11a

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
Wi-Fi® certified

**Interoperability** Wi-Fi® certified wi-Fi® certified • 802.11b/g/n

2.402 - 2.482 GHz

• 802.11a/n

4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz



## **Technical Specifications**

**Data Rates** •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

**Modulation** Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

**Network Architecture** 

Models Roaming Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Output Power<sup>2</sup>

• 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum

• 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

IEEE 802.11 compliant roaming between access points

**Power Consumption** 

• Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW
Radio disabled 8 mW

**Power Management** 

ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity 3

802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum

**Antenna type** 802.11ac, MCS9: -59dBm maximum
High efficiency antenna with spatial

High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard



## **Technical Specifications**

**Dimensions** Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
 3.3v +/- 9%

**Temperature** Operating  $14^{\circ}$  to  $158^{\circ}$  F ( $-10^{\circ}$  to  $70^{\circ}$  C)

Non-operating -40° to 176° F (-40° to 80° C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber – Radio OFF; LED White – Radio ON

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

**Bluetooth Specification** 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate<sup>1</sup> 2.17 Mbps

BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW Selective Suspend 17 mW

Bluetooth Software

Supported Link Topology

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL. CSA. and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan



## **Technical Specifications**

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

10. Sold separately or as an optional feature.

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2 x 2) and Bluetooth® 5.0 Combo¹, vPro™10,18

Wireless LAN Standards

IEEE 802.11a

IEEE 802.11b IEEE 802.11a

IEEE 802.11n

IEEE 802.11ac

IEEE 802.11ax

IEEE 802.11d

IEEE 802.11e

IEEE 802.11h

IEEE 802.11i

IEEE 802.11k IEEE 802.11r

IEEE 802.11v

Interoperability

Wi-Fi® certified

**Frequency Band** • 802.11b/g/n/ax

2.402 - 2.482 GHz

• 802.11a/n/ac/ax

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz

5.25 - 5.35 GHz

5.47 - 5.725 GHz

5.825 - 5.850 GHz

**Data Rates** • 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation **Direct Sequence Spread Spectrum** 

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security<sup>3</sup> IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification



## **Technical Specifications**

• IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

**Roaming** IEEE 802.11 compliant roaming between access points

• 802.11b: +18.5dBm minimum • 802.11a: +17.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +10dBm minimum

**Power Consumption** • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

802.11ax VHT160(5GHz): +10dBm minimum

Connected Standby 10mWRadio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity<sup>3</sup>** • 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum

802.11ax, MCS11(HT40): -59dBm maximum
802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

**Dimensions** 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

**Weight** 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating voltage 3.3v +/- 9%

**Temperature** Operating: 14° to 158° F (–10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

**Humidity** Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

**Altitude** Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)



## **Technical Specifications**

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

**Bluetooth Specification** 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

**Number of Available** 

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

**Signaling Data Rate** Legacy: 3 Mbps signaling data rate<sup>1</sup> 2.17 Mbps

BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

**Supported Link Topology** 

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support

**Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

**Bluetooth Profiles** 

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

10. Sold separately or as an optional feature.



### **Technical Specifications**

18. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

Intel® Wi-Fi 6 AX200 802.11a/b/q/n/ac/ax (2 x 2) Bluetooth® 5 Combo¹, non-vPro™10,18 Wireless LAN Standards IEEE 802.11a

> IEEE 802.11b IEEE 802.11a IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Wi-Fi certified

Interoperability **Frequency Band** 

 802.11b/g/n/ax 2.402 - 2.482 GHz • 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

**Data Rates** 

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15. (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security<sup>3</sup> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

 WPA2 certification • IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

**Network Architecture** 

Ad-hoc (Peer to Peer)

Models

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power<sup>2</sup> • 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum



## **Technical Specifications**

802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

802.11ax HT40(2.4GHz): +10dBm minimum
 802.11ax VHT160(5GHz): +10dBm minimum

**Power Consumption** • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW WLAN Associated)
Idle mode 50 mW WLAN unassociated)

Connected Standby 10mW
Radio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity**<sup>3</sup> •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
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• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac, MCS9: -59dBm maximum

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2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

**Temperature** Operating: 14° to 158° F (–10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

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**Altitude** Operating: 0 to 10,000 ft (3,048 m)

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Channels BLE: 0~39 (2 MHz/CH)

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BLE: 1 Mbps signaling data rate<sup>1</sup> 0.2 Mbps



## **Technical Specifications**

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Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

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Peak (Rx): 230 mW Selective Suspend: 17 mW

**Bluetooth Software** 

Supported Link Topology Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support

**Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

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UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 –Extended Scanner Filter Policies

LE Data Packet Length Extension

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Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

10. Sold separately or as an optional feature.

18. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

Intel® XMM™ 7360 LTE-Advanced Cat 9<sup>15</sup> Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400



### **Technical Specifications**

(Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21). 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to

450Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-A, MS-B)

**GPS** bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

**Form Factor** M.2, 3042-S3 Kev B

Weight 5.8 q

**Dimensions** 42 x 30 x 2.3 mm

(Length x Width x Thickness)

> 15. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7262 LTE-Advanced Cat 615

Technology/Operating FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 bands

(Band 8), 800 (Band 20), 700 (Band 28),

HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)

Wireless protocol

standards

300Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up to

**GPS** Standalone, A-GPS (MS-A, MS-B and XTRA)

**GPS** bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

LTE: 300 Mbps (Download), 50 Mbps (Upload) Maximum data rates

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) UMT: 384 kbps (Download), 384 kbps (Upload)

Maximum output power

LTE: 23 dBm HSPA+: 23.5 dBm

Maximum power LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

**Form Factor** M.2, 3042-S3 Key B



### **Technical Specifications**

Weight 6 g

Dimensions (Length x Width x Thickness) 42 x 30 x 2.3 mm

15. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7560 LTE-Advanced Pro Cat 16<sup>17</sup> Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band

12 lower),

700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower). 850

(Band 18 lower),

850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700

(Band 28),

700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41), 3500 (Band 42), 5200 (Band 46 RX only)

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MH

Wireless protocol

standards

3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput

up to 978Mbps; UL-CAT.13 40MHz throughput up to 150Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-B and LTO)

**GPS Bands** GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 ± 2.046 MHz

Maximum data rates LTE: 978 Mbps (Download), 150 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all bands except B41

LTE B41 HPUE: 26dBm HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 q

**Dimensions** 42 x 30 x 2.3 mm

(Length x Width x

Thickness)

17. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due



## **Technical Specifications**

to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

**NXP NPC300 Near Field Communication Module**  Dimensions (L x W x H) Module 17 mm by 10 mm by 2.0 mm

**NPC300** Chipset **System interface 12C** 

**NFC RF standards** ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

**NFC Forum Support** Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) Mode<sup>1</sup> ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

**Card Emulation (PICC-**

VICC) Mode<sup>1</sup>

ISO/IEC 14443 A ISO/IEC 14443 B and B'

**MIFARE** FeliCa

Frequency 13.56 MHz

**NFC Modes Supported** Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating temperature -25 C to 80°C Storage temperature -20°C to 125°C **Humidity** 10-90% operating

5-95% non-operating

Supply Operating voltage 2.7 to 5.5 Volts I/O Voltage 1.8V or 3.3V

10. Sold separately or as an optional feature.

**Power Consumption** (Booster enable, VBAT= 3.3V,  $VCC_BOOST = 5V$ )

**Polling** 710.93 mW Detected Test Tag Type 1 152.09 mW Detected Test Tag Type 2 341.26 mW Detected Test Tag Type 3 383.76 mW Detected Test Tag Type 4 312.26 mW

Antenna Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is

external to module.



## **Technical Specifications**

### **POWER**

HP 65W Smart AC adapter **Dimensions (H x W x D)** 107.0 x 47.0 x 30.0mm

**Weight** 250g +/- 10g

**Input Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230 Vac

**Input frequency range** 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65W

**DC output** 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <11.0A

**Connector** 4.5mm Barrel Type

**Environmental Design** Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

HP 45W Smart AC adapter Dimensions (H x W x D)

3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

 Weight
 0.386 lb (175g) max

 Input
 90 to 265 VAC

Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac

Input frequency range 47 to 63 Hz
Input AC current 1.4 A at 90 VAC

Output Output power 45W

DC output 19.5V

**Hold-up time** 5 msec at 115 VAC input

Output current limit <8.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

**Environmental Design** Operating 32° to 95°F (0° to 35°C)

temperature



## **Technical Specifications**

Non-operating (storage) -4° to 185°F (-20° to 85°C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** Certifications

Weight

CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1. SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W EM **Smart AC adapter**  Dimensions (H x W x D)

270g +/- 10g

Input

**Input Efficiency** 87% min at 115V/230V

Input frequency range

47 to 63 Hz

**Input AC current** 

102 x 55 x 30mm

1.7 A at 90 VAC and maximum load

Output **DC** output 65W(19.5V/3.33A)

Hold-up time

5 msec at 115 VAC input

**Output current limit** 

<11A, Over voltage protection- 29V max

automatic shutdown

Connector

4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

**Environmental Design** 

**Operating** temperature 0° to 35° C

Non-operating (storage) -20° to 85° C

temperature

**Altitude** 

0 to 5,000 m

**Humidity** 

0% to 95%

**Storage Humidity** 

0% to 95%

**EMI and Safety** Certifications

CE Mark - EMC directives: Worldwide safety standards

-IEC60950, EN60950, UL60950, Class1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B. CCC, NOM-1 NYCE; Reliability - failure rate of less than 0.1% annually

within the first three years of operation.



## **Technical Specifications**

Input

Output

AC Adapter 45 Watt nPFC USB type C™ Dimensions (H x W x D) 62.0 x 62.0 x 28.5 mm

Weight unit: 220g +/- 10g

**Input Efficiency** Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:5V: 81.5%9V: 86.7%10V: 87.5%12V: 87.8%15V:

87.8%20V:87.8%

**Input frequency range** 47 ~ 63Hz

Input AC current Max. 1.4 A at 90 Vac

Output Power 5V/15W

9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W

**DC output** 5V / 9V / 10V /12V / 15V / 20V

**Hold-up time** 5ms at 115 Vac input

Output current limit <5.0A

**Connector** USB Type-C™

**Environmental Design** Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

**Altitude** 0 to 16.400 ft (0 to 5000m)

AC Adapter 65 Watt nPFC USB type C ™ **Dimensions (H x W x D)** 74 x 74 x 28.5 mm

**Weight** unit: 245g +/- 10g

Input Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

**Input frequency range** 47 ~ 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output Output Power 65W

**DC output** 5V/9V/10V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

Connector Duck head / duck head power cord, without Smart ID DC connector

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature



## **Technical Specifications**

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% Storage Humidity 5% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 100,000 hours at 25°C ambient condition.

HP 4 Cell WHr 53 Long Life -PL Fast Charge Dimensions (H x W x D)

5.58 mm \* 80.62 mm \* 269.2 mm

Weight

243g

Cells/Type

3-cell; Polymer

Energy Voltage

Amp-hour capacity 6.9Ah

Watt-hour capacity 53.2Wh

Temperature

**Operating (Charging)**  $0^{\circ}\text{C} \sim 45^{\circ}\text{C}$ 

14° to 122°F (-10° to 60°C)

Operating (Discharging)
Optional Travel Battery

No

7.7V

Available

### **Country of Origin**

China



## Options and Accessories (Sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Basic Backpack	H1D24AA
	HP Slim Top Load	F3W15AA
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 120W G2 TAA	2UK37AA
	HP Elite 90W Thunderbolt 3 Dock	1DT93AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP USB-C Travel Dock	TOK29AA
	HP USB Travel Dock	TOK30AA
	HP USB-C Universal Dock	1MK33AA
	HP Adjustable Dual Display Stand	AW664AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse to AMO	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2CE30AA
	HP USB-C to USB 3.0 Adapter	N2Z63AAA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to HDMI 2.0	1WC36AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP USB-C to RJ45	V7W66AA
	HP USB to RJ45	N7P47AA
	HP HDMI to VGA	H4F02AA
Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 90W Slim AC Adapter	H6Y83AA



## Options and Accessories (Sold separately and availability may vary by country)

	UD could's contract to the	1151/5 4 4 4
	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	1TZ86AA
UCC	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA
	HP UC Wireless Duo Headset	W3K09AA
Storage	HP USB External DVDRW Drive	F2B56AA
	HP 256GB M2 PCIe NVME SSD TLC (2280)	1FU87AA
	HP 512GB M2 PCIe NVME SSD TLC 2280)	1FU88AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Dual-Head Keyed Cable Lock	1AJ41AA
Other	HP TB Dock Audio Module	3AQ21AA
	HP Thunderbolt 120W 1m cable	3AQ23AA
	HP Thunderbolt 1m combo cable	3A25AA
	HP Rechargeable Active Pen	4KL69AA
Displays	HP EliteDisplay E243d 23.8-inch Docking Monitor	1TJ76AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay E273q 27-inch Monitor	1FH52AA



## **Change Log**

Date of change:	Version History:		Description of change:
June 10, 2019	From V1 to V2	Added	HP Cloud Recovery
June 20, 2019	From V2 to V3	Added	Environmental tab
July 2, 2019	From V3 to V4	Updated	Color Gamut
September 9, 2019	From V4 to V5	Updated	Intel® Optane™ and disclaimer for 1000 nit Sure View panel
November 6, 2019	From V5 to V6	Updated	Processors section
January 21, 2020	From V6 to V7	Added	Modern Connected Standby

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